

Procedure file

Basic information		
DEA - Delegated acts procedure	2018/2947(DEA)	Procedure completed - delegated act enters into force
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages Supplementing 2008/0240(COD) Subject 3.40.06 Electronics, electrotechnical industries, ICT, robotics 3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)		

Key players			
European Parliament	Committee responsible	Rapporteur	Appointed
	ENVI Environment, Public Health and Food Safety		

Key events			
16/11/2018	Non-legislative basic document published	C(2018)07499	
16/11/2018	Initial period for examining delegated act 2 month(s)		
28/11/2018	Committee referral announced in Parliament		
24/01/2019	Delegated act not objected by Parliament		

Technical information	
Procedure reference	2018/2947(DEA)
Procedure type	DEA - Delegated acts procedure
Procedure subtype	Examination of delegated act
Stage reached in procedure	Procedure completed - delegated act enters into force
Committee dossier	ENVI/8/15029

Documentation gateway					
Non-legislative basic document		C(2018)07499	16/11/2018	EC	